

EAST Search History

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	55662	(leadframe leadfinger (lead adj (finger frame))) with (semiconductor die chip dice ic (integrated adj circuit) electronic microelectronic microprocessor element loc (lead adj2 chip))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/03/30 14:56
L2	5267	(ball bump bga) same 1	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/03/30 14:57
L3	1783	(encase encapsulat\$4 encapsulant epoxy resin) same 2	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/03/30 14:57